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FOREIGN PATENT DOCUMENTS

		Document No.	Date	Country	Translation (Yes or No)
<i>MN</i>	AA	56-148068	11/17/81	Japan	Abstract
<i>J</i>	AB	04-083343	3/17/92	Japan	Abstract
<i>J</i>	AC	2001-060605	3/6/01	Japan	Abstract

OTHER DOCUMENTS

<i>MN</i> <hr/> <hr/> <hr/> <hr/> <hr/>	AD	Research Report RC162, Special Interest Group on Reliability Assessment for Electronics Packaging, Chapter 20, May 11, 2000 (whole translation)		
	AE	7 th Symposium on Microjoining and Assembly Technology in Electronics, 2001, pp. 35-40 (whole translation)		
	AF	7 th Symposium on Microjoining and Assembly Technology in Electronics, 2001, pp. 41-46 (whole translation)		
	AG	Analysis of Phase Growth Process in SN/PB Eutectic Solder Joint, EEP-Vol. 26-1, Advance in Electronic Packaging; Editors: D. Agonafter, M. Saka, and Y.C. Lee Bok. No. G1107A-1999		
	AH	A Microstructural Evaluation Method of Thermal Fatigue Crack Initiation in SN/PB Eutectic Solder Joints, IPACK2001-15572, Proceedings of IPACK'01, The Pacific Rim/ASME International Electronic Packaging Technical Conference and Exhibition, July 8-13, 2001, Kauai, Hawaii, USA		
Examiner		<i>Noori</i>	Date Considered	<i>5/10/06</i>